

DURAPOT™ EPOXIES

High Performance Casting, Embedding and Encapsulating Compounds For Electronic Applications

Durapot™ 861 Low Viscosity Impregnant

A 100% reactive compound for use to 500°F. 861's low viscosity will provide excellent penetration even into tightly wound coils.

Just mix and cure at room temp. and has excellent electrical, moisture and chemical resistance. Available in flame retardant grades.

Durapot™ 862 High Temp. Low Viscosity

A 100% reactive compound for use to 600°F. 862's low viscosity provides excellent penetration.

Usable to temperatures in the 600°F range. 862 cures at 250°F and has excellent electrical, moisture and chemical resistance.

Durapot™ 863 Ultra High Temp Potting

Durapot™ 863 is based on Cotronics' unique, Cross-Linked, Inorganic-Organic Polymer, System. Offers excellent dielectric properties, heat stability, moisture and solvent resistance.

Usable to temperatures in the 600°F range after curing at 250°F.

Durapot™ 864 Flexible, Cures at Room Temp.

Provides the flexibility required for severe thermal shock applications. Will bond to dissimilar materials, treated TEFLON™ and other difficult to bond plastics and offers up to 450°F continuous service.

Users Report the ability to impregnate and bond thousands of small diameter, fiber optical strands for use at 500°F.

Ideal for stress free embedding, impregnating and encapsulation. Available in flame retardant grades.

Durapot™ 865 High Thermal Conductivity

For applications requiring high heat flows and rapid thermal dissipation. Just mix, apply and cure at room temp. Usable to 500°F. Used for thermally conductive, casting, embedding, impregnating and encapsulation.

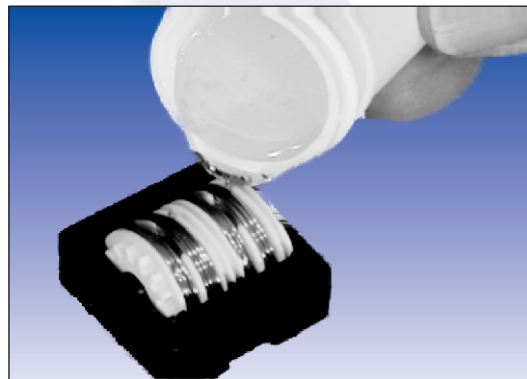
Durapot™ 866 Thermally Insulating

A 500°F epoxy based, thermally and electrically insulating compound. Convenient two part, room temperature curing system. Forms a low density, non porous foam for high temperature applications that require these unusual combinations of properties. Available in flame retardant grades.

Durapot™ 868 Hi-Temperature Flexible

Now, a high temp. flexible epoxy ideal for thermal shock applications, stress free potting and bonding.

Durapot™ 868 offers high electrical resistance, even at high temperatures, and can be used up to 500°F.



**Durapot™ 864 is Used to Pot an
Electronic Assembly to
Prevent Vibration Damage**

Cat. No.	Description	Pre-Measured Kits	Pre-Measured Kits
Durapot™ 861.....	500°F Low Viscosity	Ten-10 gm units	Ten-25 gm units
Durapot™ 861IP.....	500°F Low Viscosity	Ten-10 gm units	Ten-25 gm units
Durapot™ 862.....	600°F Low Viscosity	Ten-10 gm units	Ten-25 gm units
Durapot™ 863.....	650°F Low Viscosity	Ten-10 gm units	Ten-25 gm units
Durapot™ 864.....	450°F Flexible, Shock Resistant	Ten-10 gm units	Ten-25 gm units
Durapot™ 865.....	500°F Thermally Conductive	Ten-10 gm units	Ten-25 gm units
Durapot™ 865IP.....	500°F Thermally Conductive	Ten-10 gm units	Ten-25 gm units
Durapot™ 866.....	500°F Thermally Insulating	Ten-10 gm units	Ten-25 gm units
Durapot™ 868.....	500°F High Temp. Shock Resist	Ten-10 gm units	Ten-25 gm units

All Durapot materials can be supplied convenient job sited, pre-measured kits and in bulk.
New, slow set hardeners formulated to make large castings and parts are available upon request.

Quantity Pricing is Available Upon Request

DURAPOT™ EPOXIES

High Performance Casting, Embedding and Encapsulating Compounds

Durapot™	861	862	863	864	865	866	868
Max Temp.	500°F	600°F	600°F	450°F	500°F	500°F	500°F
FEATURES	Low Visc. Impregnant R.T. Cure	Low Visc. High Temp.	Ultra High Temp.	Flexible Thermal Shock	High Thermal Shock	Thermal Insulating Machinable	Hi-Temp Flexible Low Visc.
Volume Resistivity (ohm-cm)	10 ¹³	10 ¹⁴	10 ¹⁴	10 ¹⁴	10 ¹⁵	10 ¹⁵	10 ¹⁴
Dielectric Strength (volts / mil)	450	500	550	450	700	500	500
Dielectric Constant	4.15	4.15	3.5	3.5	3.5	3.5	4.1
Dissipation Factor	0.015	0.015	0.010	0.010	0.010	0.015	0.015
Thermal Exp. (10 ⁻⁵ / °C)	12.4	9.8	10.1	6.8	3.8	4.5	5.2
Therm. Cond. (BTU in/hr.F°ft ²)	1.47	1.76	1.81	7	13	1.5	4.0
Hardness (Shore)	80-D	80-D	90-D	60-80A	95D	60-D	60-80A
Chemical Resistivity	Excellent	Excellent	Excellent	Good	Excellent	Excellent	Excellent
Solvent Resistance	Excellent	Excellent	Excellent	Good	Excellent	Excellent	Excellent
Viscosity, Mixed (cps)	3,600	1,600	2,000	17,200	30,000	10,000	800
Pot Life (Hrs.)	30 mins.	4	8	1	1	1	2-4
Color	Amber	Amber	Amber	Tan	Grey	Tan	Amber
Components	2	2	2	2	2	2	2
Mix Ratio by Wt.	100/17	100/80	100/71	100/120	100/5	100/12	100/40
Standard Cure Temp. °F Time (Hrs.)	R. T. 16-24	250 4	250 4	R. T. 24	77 16-24	R. T. 24	250 2-4
Accelerated Cure Cycle Time @ Temp °F (25 gms)	5 mins. @ 250	60 mins. @ 350	1-2 hrs. @ 350	1-2 hrs. @ 250	10 mins. @ 250	10 mins. @ 250	60 mins. @ 350

Pre-Measured Kits

Post cures @ 250°F will improve moisture resistance for 861, 864, 865, 866.

Epox-Eez™ in 10 gm. and 25 gm. Units (Page 19)